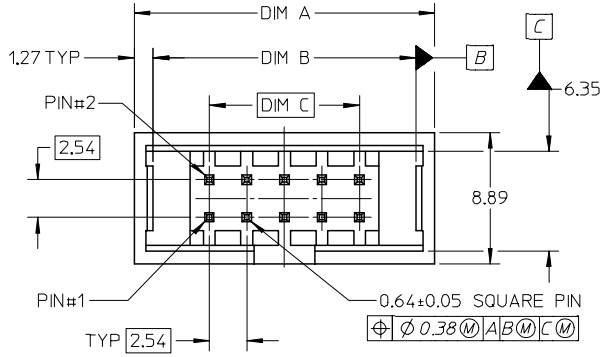
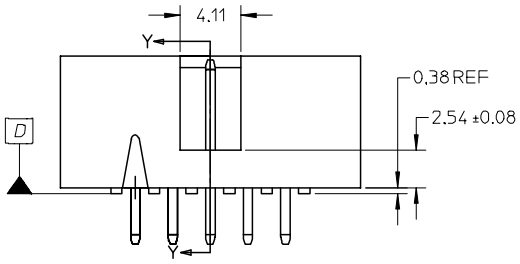
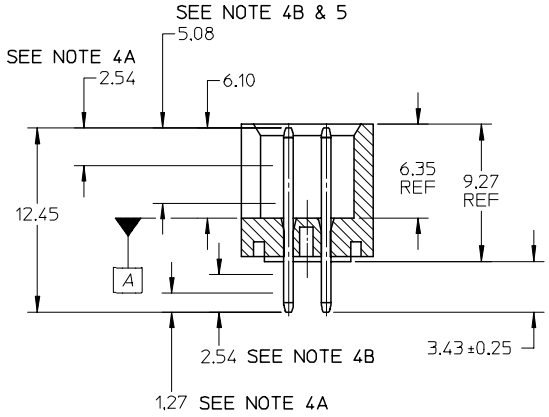
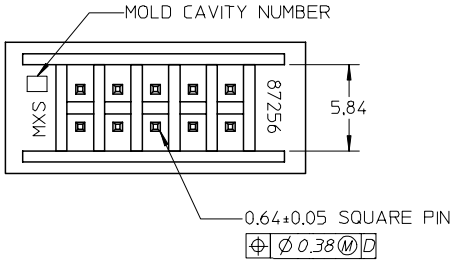
| PART NUMBERS | CKT SIZE | VOIDED PIN LOCATION | DIM A | DIM B | DIM C |
|---|---|---|---|---|---|
| 87834-3443 | 34 | 5 | 50.80 | 48.26 | 40.64 |
| 87834-4043 | 40 | 20 | 58.42 | 55.88 | 48.26 |
| 87834-4143 | 40 | 25,27,28 | 58.42 | 55.88 | 48.26 |



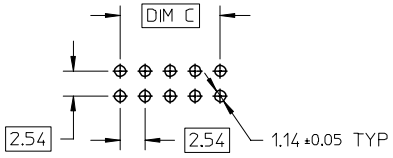




SECTION Y-Y




NOTES :

1. MATERIAL :-
   HOUSING : NYLON (PA), UL94V-0, COLOR: BIEGE.
   PIN : COPPER ALLOY.
2. FINISH :
   TERMINAL : SELECTIVE GOLD IN THE CONTACT,
   THICKNESS= 0.38 MICROMETER MINIMUM;
   SELECTIVE PURE TIN IN THE PC TAIL AREA,
   THICKNESS= 2.54 MICROMETER MINIMUM;
   NICKEL UNDERPLATE
3. PRODUCT SPECIFICATION PS-70246-100 APPLIES.
4. DIMENSIONS FOR PLATING LOCATIONS :
   A - MEASURE POINT FOR THICKNESS
   B - MINIMUM COVERAGE.
5. WAFER TO BE FLAT WITHIN 0.003 MILLIMETER/MILLIMETER
6. FOR ILLUSTRATION PURPOSE, A 10 CIRCUIT SIZE IS SHOWN.




RECOMMENDED PCB PATTERN

ADD MATERIAL NOTE
EC NO: S2005-0319 2004/12/08
DRWN:ATSEE 2004/12/09
CH'KD:SHONG 2004/12/13
APPR:SKTOH
DESCRIPTION
A1
REV

QUALITY SYMBOLS
▼=0
▽C=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

| | mm | INCH |
|---|---|---|
| 4 PLACES | ± --- | ± --- |
| 3 PLACES | ± --- | ± --- |
| 2 PLACES | ± 0.20 | ± --- |
| 1 PLACE | ± --- | ± --- |
| ANGULAR ± 1 ° | | |

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: RSHAN DATE: 2004/01/14
CHECKED BY: KCLING DATE: 2004/01/30
APPROVED BY: SKTOH DATE: 2004/01/30

TITLE: C-GRID, SHROUDED WAFER WITH VOIDED AND W/O END SLOT, POLARIZING PEGS

molex MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-87834-030
SHEET NO.: 1 OF 1
SIZE: A3

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